

## NTE5332 & NTE5334

### Silicon Bridge Rectifier, 1A

#### **Features:**

- Glass Passivated Chip Junctions
- Surge Overload Rating: 50A (Peak)
- Ideal for Printed Circuit Board
- High Temperature Soldering Guaranteed: +285°C/10 seconds at 5 lbs., (2.3kg) tension

#### **Maximum Ratings and Electrical Characteristics:** ( $T_A = +25^\circ\text{C}$ unless otherwise specified, 60Hz, Resistive or Inductive Load.)

Maximum Recurrent Peak Reverse Voltage, $V_{RRM}$	
NTE5332 .....	600V
NTE5334 .....	1000V
Maximum RMS, $V_{RMS}$	
NTE5332 .....	420V
NTE5334 .....	700V
Maximum DC Blocking Voltage, $V_{DC}$	
NTE5332 .....	600V
NTE5334 .....	1000V
Maximum Average Forward Output Rectified Current ( $T_A = +40^\circ\text{C}$ ), $I_{O(AV)}$	1A
Peak Forward Surge Current (Single Sine-Wave Superimposed on Rated Load), $I_{FSM}$	50A
Rating for Fusing ( $t < 8.35\text{ms}$ ), $I^2t$	10A <sup>2</sup> s
Maximum Instantaneous Forward Voltage Drop (Per element at 1A), $V_F$	1.2V
Maximum Reverse Current at Rated DC Blocking Voltage Per Element, $I_R$	
$T_A = +25^\circ\text{C}$ .....	10 $\mu\text{A}$
$T_A = +125^\circ\text{C}$ .....	500 $\mu\text{A}$
Typical Junction Capacitance Per Element (Note 1), $C_J$	25pf
Typical thermal Resistance (Note 2), $R_{\theta JA}$	+40°C/W
Operating Junction Temperature Range, $T_J$	-65° to +150°C
Storage Temperature Range, $T_{stg}$	-65° to +150°C

Note 1. Measured at 1.0MHz and applied reverse voltage of 4.0 Volts.

Note 2. Thermal Resistance from Junction to Ambient mounted on P.C. Board with 0.5" x 0.5" (13mm x 13mm) Copper Pads.

